-30V P-Channel Enhancement Mode MOSFET

MTE040P03N3

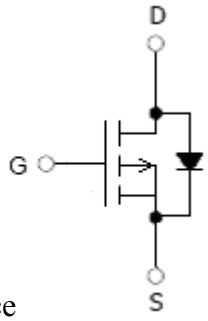
BV_{DSS}	-30V
I_D @ V_{GS}=-10V, T_A=25°C	-4A
R_{DSON}@V_{GS}=-10V, I_D=-4.5A	42mΩ(typ)

Features

- Compact and low profile SOT-23 package
- Advanced trench process technology
- High density cell design for ultra low on resistance
- Pb-free lead plating package

Symbol

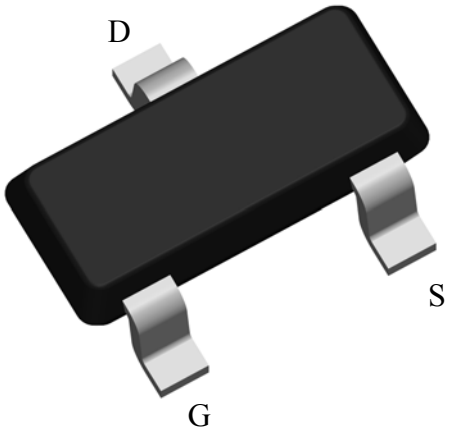
MTE040P03N3



G：Gate
S：Source
D：Drain

Outline

SOT-23



Ordering Information

Device	Package	Shipping
MTE040P03N3-0-T1-G	SOT-23 (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel

Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T1 : 3000 pcs / tape & reel, 7” reel

Product rank, zero for no rank products

Product name

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	±20	
Continuous Drain Current @ T_A=25°C , V_{GS}=-10V (Note 3)	I_D	-4	A
Continuous Drain Current @ T_A=70°C, V_{GS}=-10V (Note 3)		-3.2	
Pulsed Drain Current (Notes 1, 2)	I_{DM}	-24	
Maximum Power Dissipation (Note 4)	P_D	1.25	W
Linear Derating Factor		0.01	W/°C
Operating Junction and Storage Temperature Range	Tj ; Tstg	-55~+150	°C

Note : 1. Pulse width limited by maximum junction temperature.
2. Pulse width≤ 300μs, duty cycle≤2%.
3. Surface mounted on 1 in² copper pad of FR-4 board; 270°C/W when mounted on minimum copper pad

Thermal Performance

Parameter	Symbol	Limit	Unit
Thermal Resistance, Junction-to-Ambient (PCB mounted)	$R_{\theta JA}$	100	°C/W
Thermal Resistance, Junction-to-Case , max	$R_{\theta JC}$	45	

Note : Surface mounted on 1 in² copper pad of FR-4 board; 270°C/W when mounted on minimum copper pad

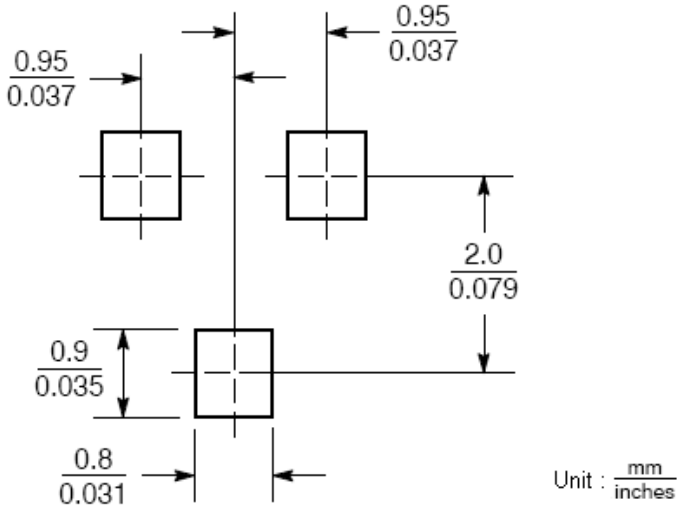
Electrical Characteristics (Tj=25°C, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	-30	-	-	V	V_{GS}=0V, I_D=-250μA
$\Delta BV_{DSS}/\Delta Tj$	-	0.01	-	V/°C	Reference to 25°C, I_D=-250μA
$V_{GS(th)}$	-2	-	-4	V	V_{DS}=V_{GS}, I_D=-250μA
I_{GSS}	-	-	±100	nA	V_{GS}=±20V, V_{DS}=0V
I_{DSS}	-	-	-1	μA	V_{DS}=-24V, V_{GS}=0V
	-	-	-10		V_{DS}=-24V, V_{GS}=0V (Tj=70°C)
*$R_{DS(ON)}$	-	42	53	mΩ	V_{GS}=-10V, I_D=-4A
*G_{FS}	-	3.4	-	S	V_{DS}=-10V, I_D=-3A
Dynamic					
*Qg	-	10.3	-	nC	V_{DS}=-24V, I_D=-4A, V_{GS}=-10V
*Qgs	-	2.5	-		
*Qgd	-	2.8	-		
*$t_{d(ON)}$	-	7.6	-	ns	V_{DS}=-15V, I_D=-4A, V_{GS}=-10V, R_G=1Ω
*t_r	-	15.8	-		
*$t_{d(OFF)}$	-	34.8	-		
*t_f	-	12.6	-		

Ciss	-	482	-	pF	V_{DS}=-25V, V_{GS}=0V, f=1MHz
Coss	-	65	-		
Crss	-	50	-		
Source-Drain Diode					
*V_{SD}	-	-0.78	-1.2	V	V_{GS}=0V, I_S=-1A
Trr	-	8.2	-	ns	V_{GS}=0V, I_F=-1A, dI_F/dt=100A/μs
Qrr	-	3.3	-	nC	

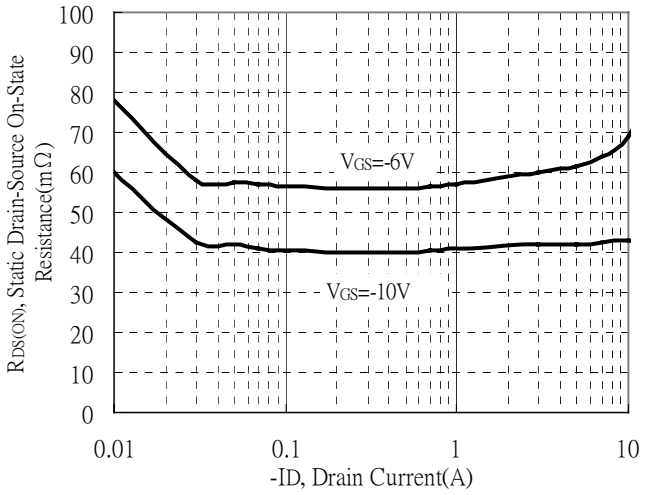
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Recommended Soldering Footprint

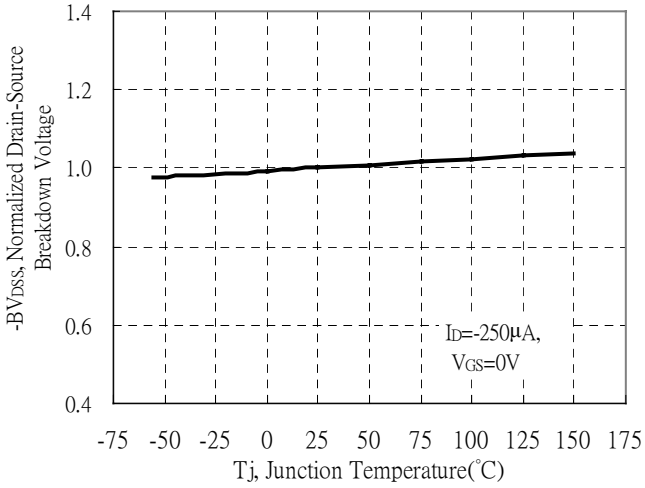


Typical Characteristics

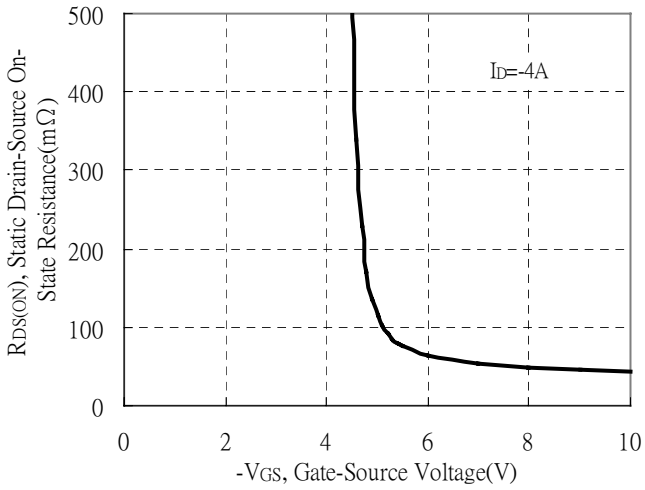
Static Drain-Source On-State resistance vs Drain Current



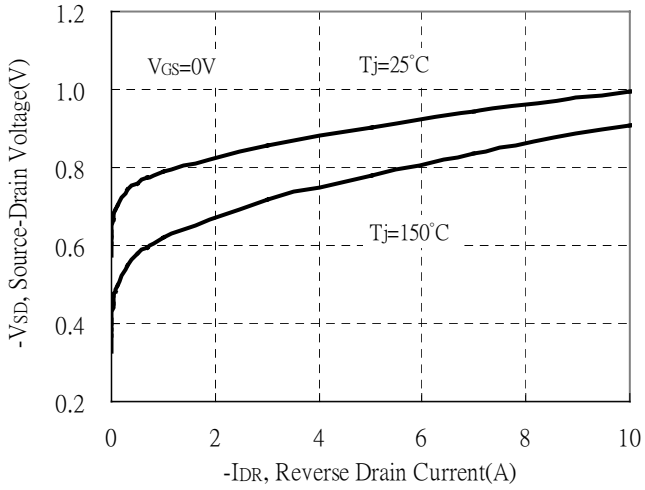
Brekdown Voltage vs Ambient Temperature



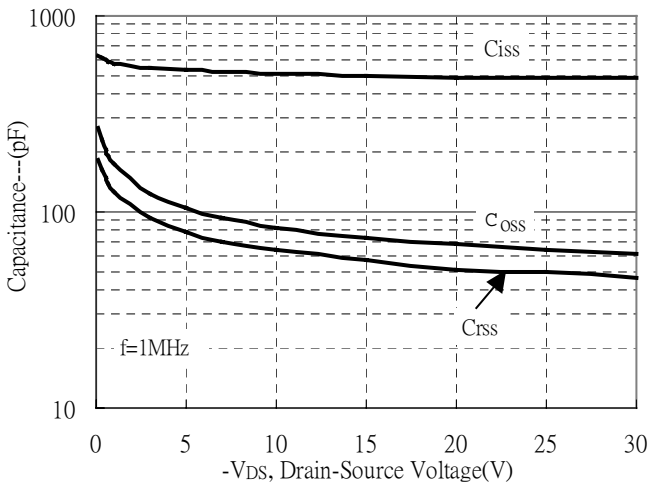
Static Drain-Source On-State Resistance vs Gate-Source Voltage



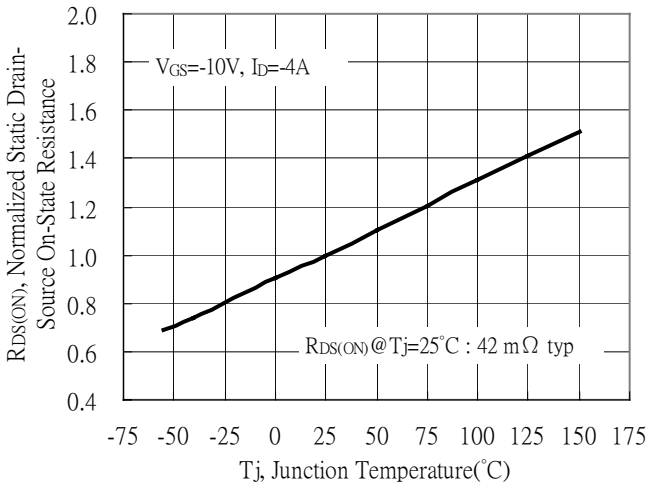
Reverse Drain Current vs Source-Drain Voltage



Capacitance vs Drain-to-Source Voltage

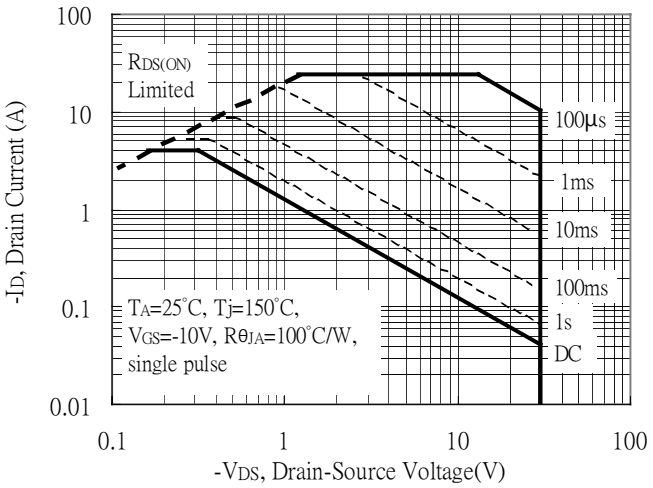


Drain-Source On-State Resistance vs Junction Tempearture

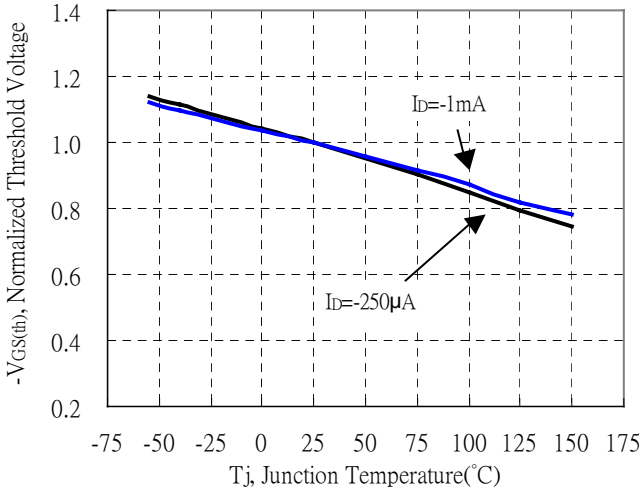


Typical Characteristics(Cont.)

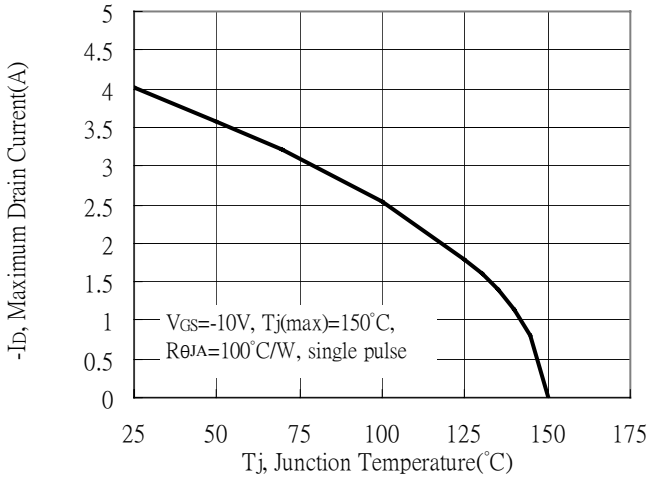
Maximum Safe Operating Area



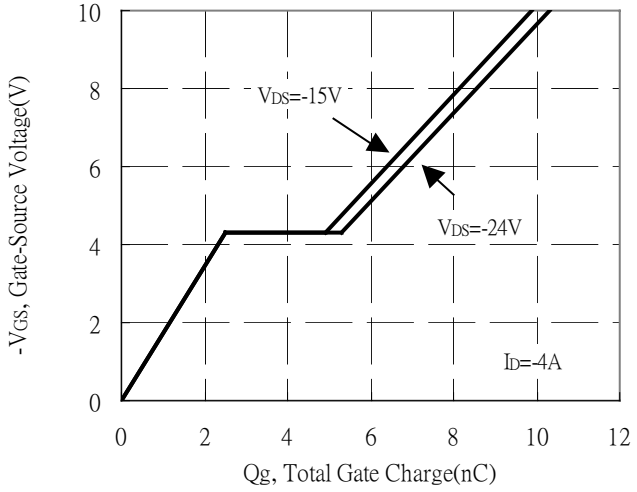
Threshold Voltage vs Junction Tempearture



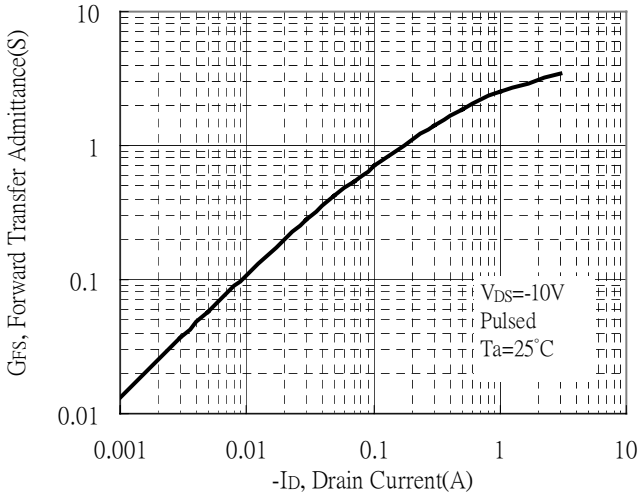
Maximum Drain Current vs Junction Temperature



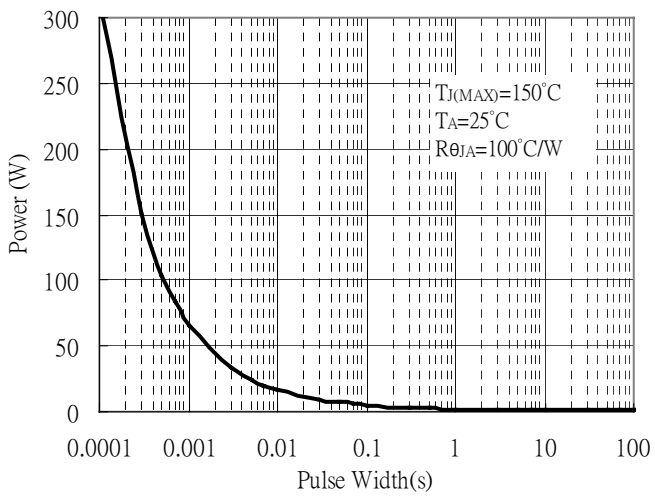
Gate Charge Characteristics



Forward Transfer Admittance vs Drain Current

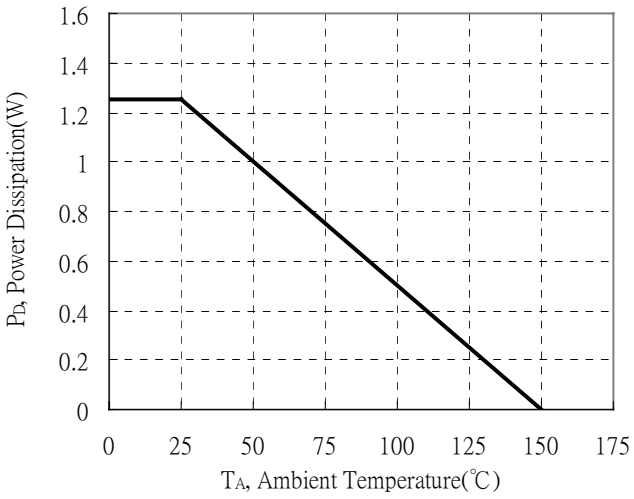


Single Pulse Power Rating, Junction to Case

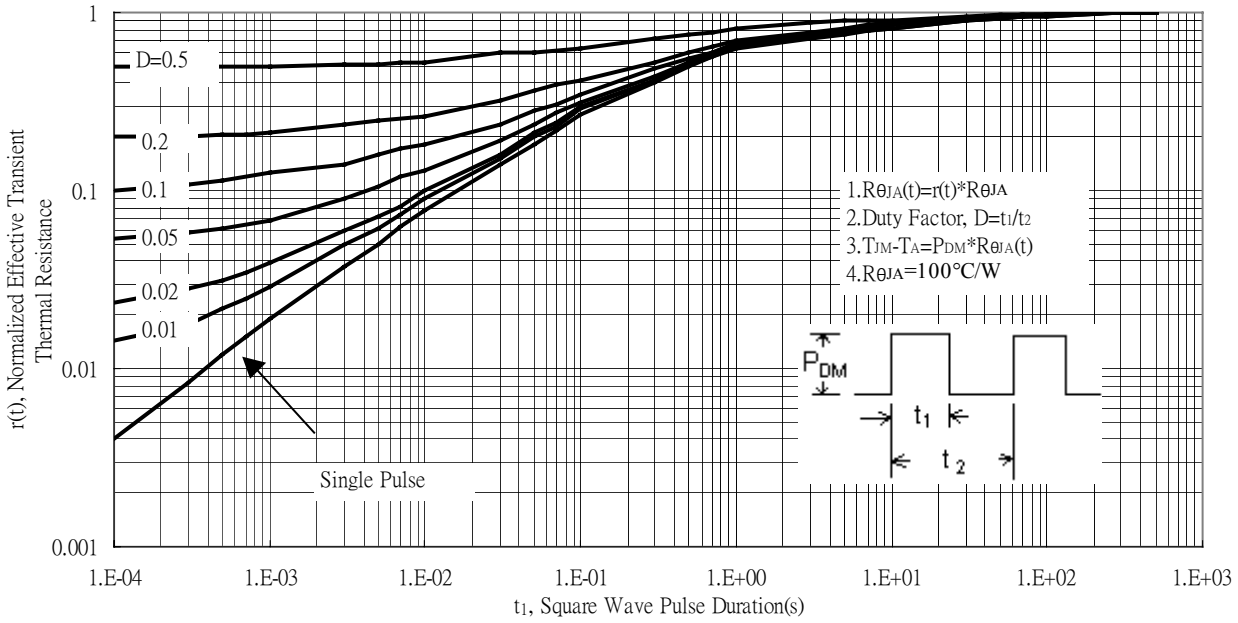


Typical Characteristics(Cont.)

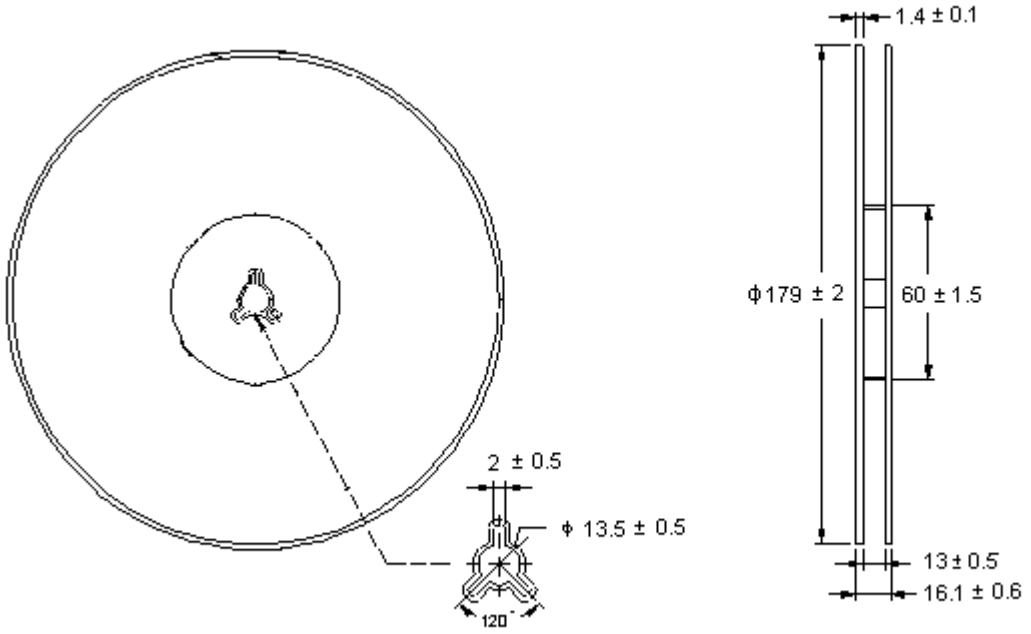
Power Derating Curve



Transient Thermal Response Curves

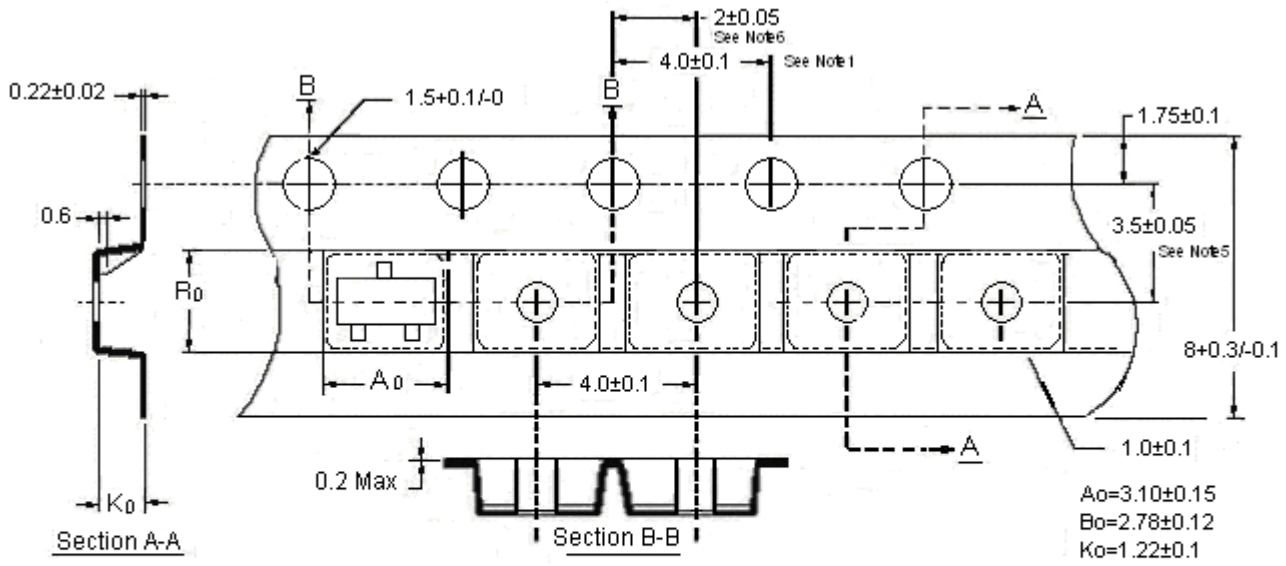


Reel Dimension



Unit: millimeter

Carrier Tape Dimension



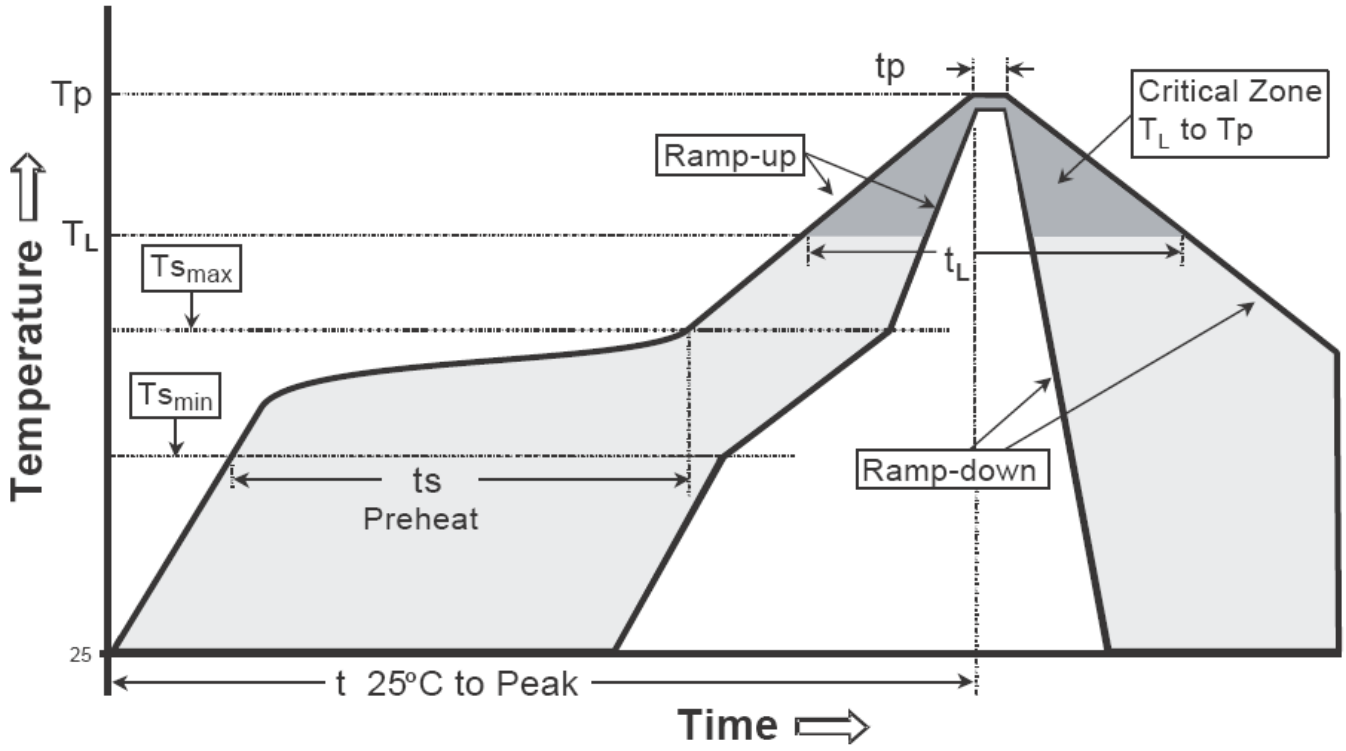
Notes:
1. 10 sprocket hole pitch cumulative tolerance ±0.2.
2. Camber not to exceed 1mm in 100mm.
3. Material : conductive Black Polystyrene.
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Unit : millimeter

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

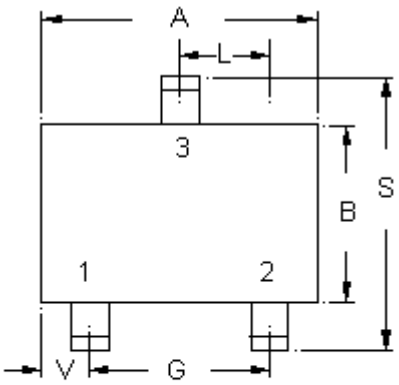
Recommended temperature profile for IR reflow

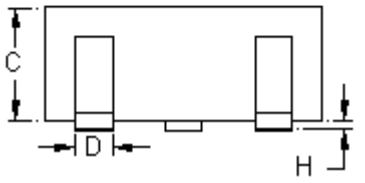


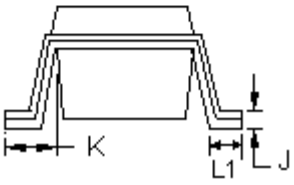
Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(Ts min) −Temperature Max(Ts max) −Time(ts min to ts max)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (TL) − Time (tL)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

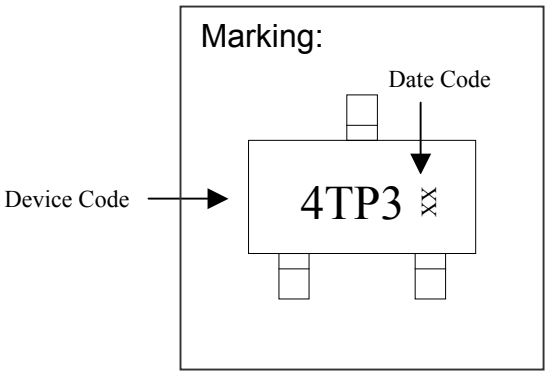
Note :1. All temperatures refer to topside of the package, measured on the package body surface.
2.For devices mounted on FR-4 PCB of 1.6mm or equivalent grade PCB. If other grade PCB is used, care should be taken to match the coefficients of thermal expansion between components and PCB. If they are not matched well, the solder joints may crack or the bodies of the parts may crack or shatter as the assembly cools.

SOT-23 Dimension









3-Lead SOT-23 Plastic
Surface Mounted Package
CYStek Package Code: N3

Style: Pin 1.Gate 2.Source 3.Drain

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0032	0.0079	0.08	0.20
B	0.0472	0.0669	1.20	1.70	K	0.0118	0.0266	0.30	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1161	2.10	2.95
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0000	0.0040	0.00	0.10	L1	0.0118	0.0197	0.30	0.50

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.